

Metallic SOFC Interconnect Systems

J.M. Rakowski
ATI Allegheny Ludlum



Allegheny Technologies

Building the World's Best Specialty Metals Company

Overview

- Surface modification of ferritic (Fe-Cr) stainless steels has shown promise in mitigating the detrimental effects of aluminum and silicon
- Multi-layered interconnect structures have been tested and shown to be effective in eliminating or reducing oxidation on the anode side of the SOFC interconnect

Overview

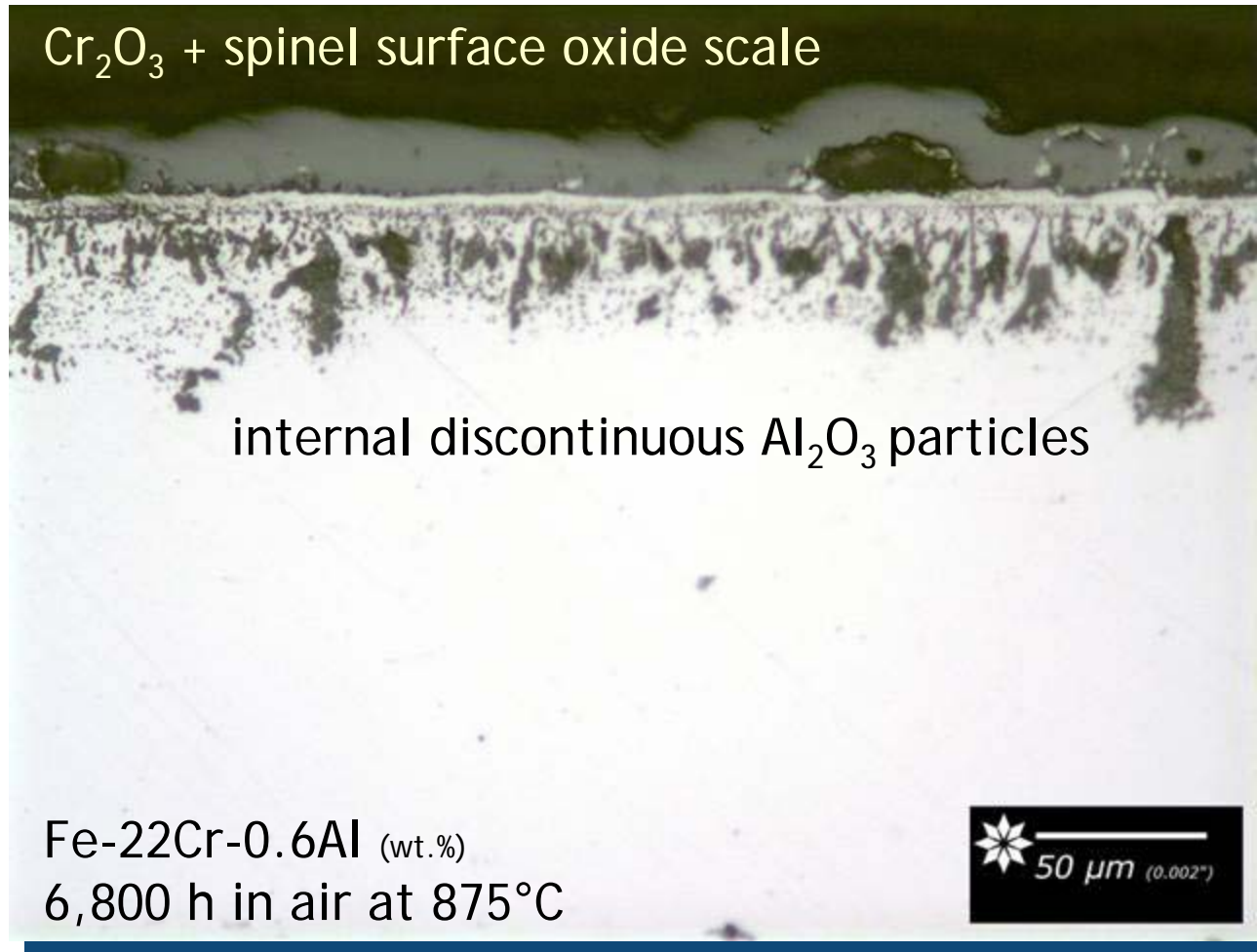
- Some of the alloys tested for anode-side layers may possibly reduce hydrogen transport effects
- Other results
 - Alloy development
 - Evaluation of oxidation-resistant, electrically conductive coatings
 - Surface layer adhesion (CMU)
 - Contact layer development (WVU)

Post-Process Surface Modification Effect on ASR

Surface Modifications

- Aluminum and silicon in Fe-Cr alloys generally come from additions made during the steelmaking process
- Both elements have a high affinity for oxygen and form electrically resistive oxides at the scale/alloy interface

Internal Oxidation of Aluminum



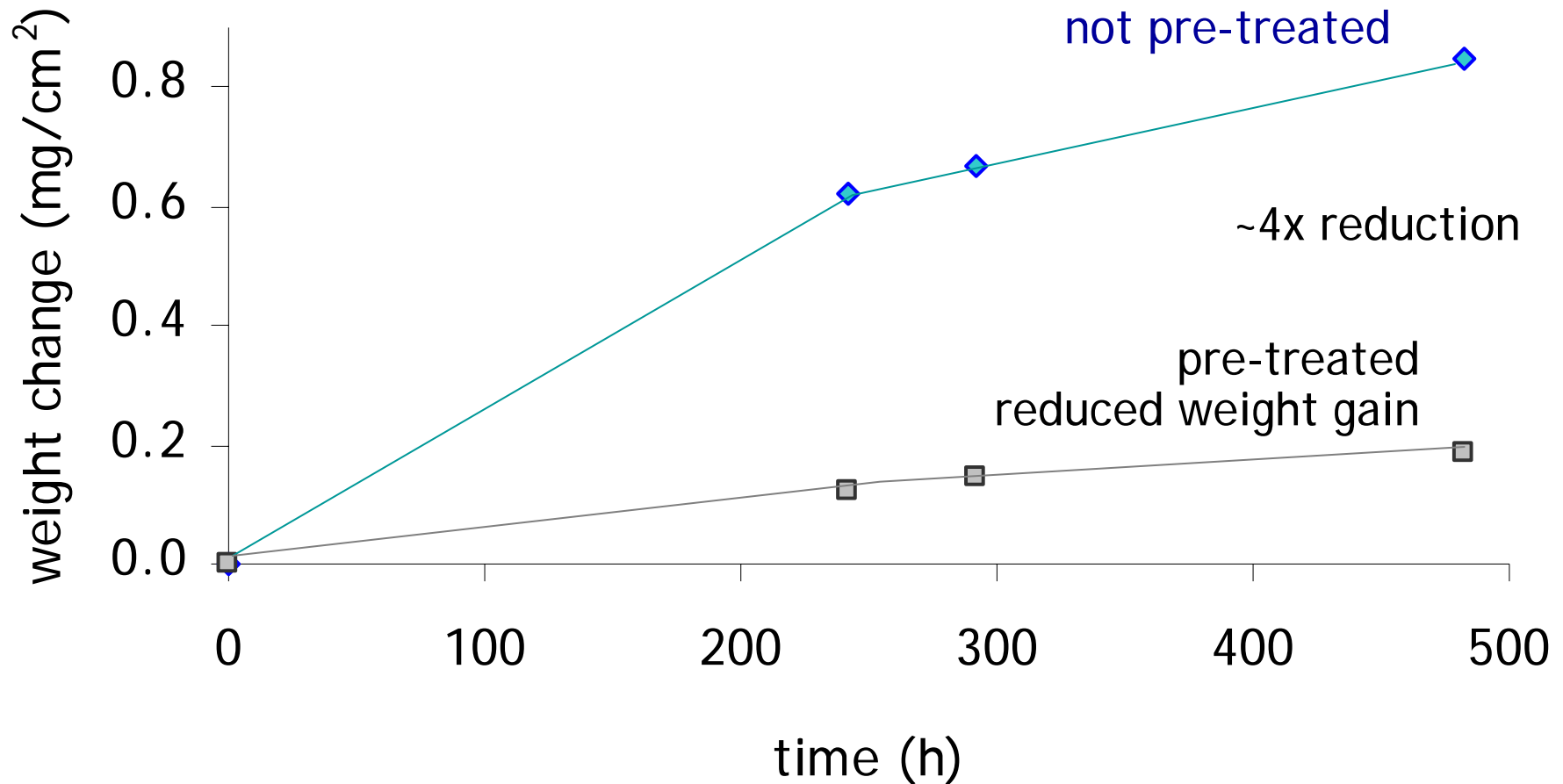
Surface Modifications

- Surface processing of stainless steel after manufacturing
 - Aluminum sequestration
 - Silicon removal
- Beneficial effect on ASR observed in preliminary evaluation of pre-oxidized specimens

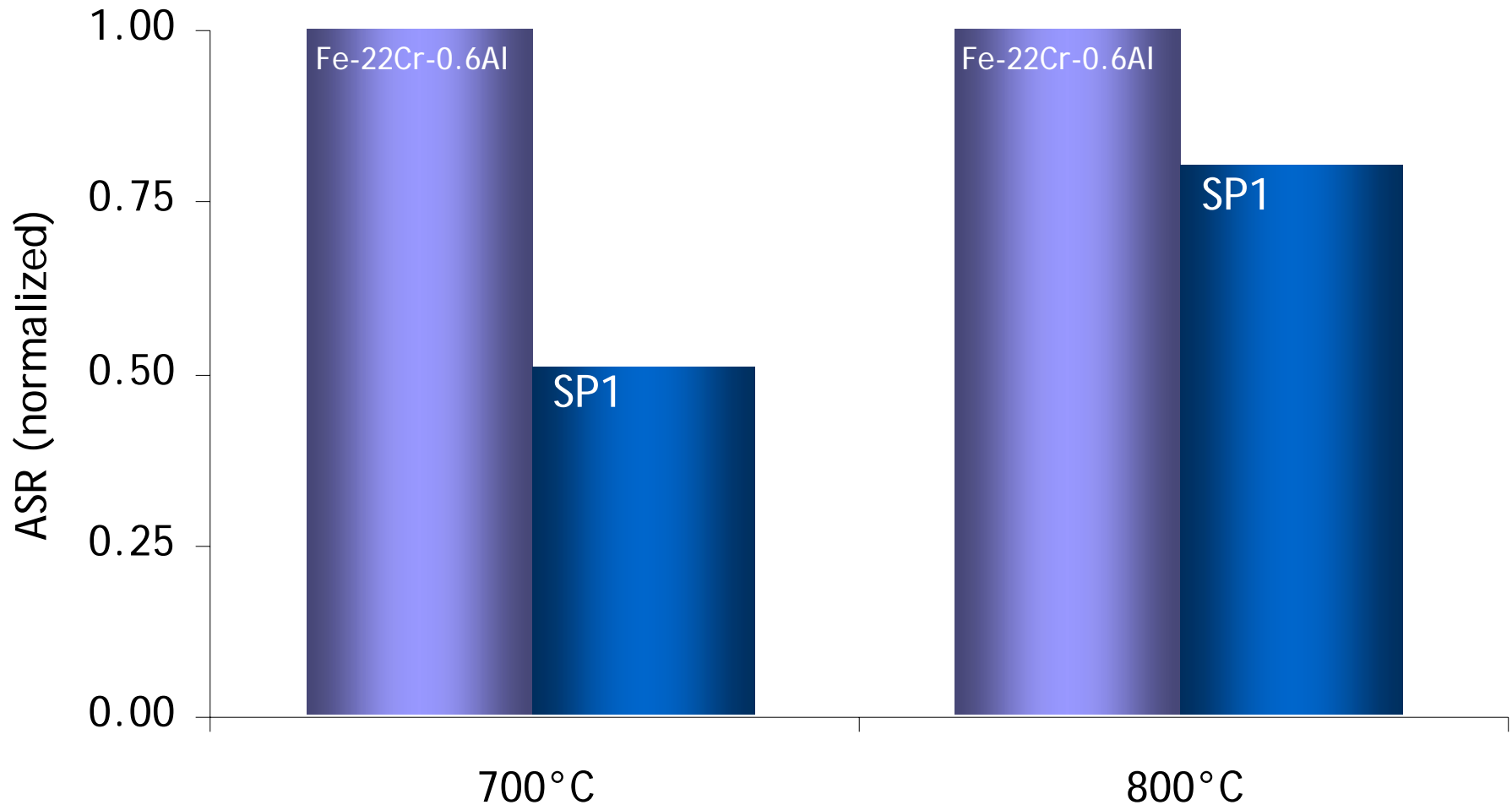
Effect of Aluminum Sequestration

- Aluminum forms internal oxide particles at the scale/alloy interface
 - Increases oxygen uptake (higher weight gains during oxidation testing)
 - Reduces electrically conductive cross-section
- Special processing sequesters aluminum
 - Reduced weight gain (no internal oxidation)
 - Lower ASR
 - Effect reduced at higher temperatures

Effect of Aluminum Sequestration on Oxidation Kinetics



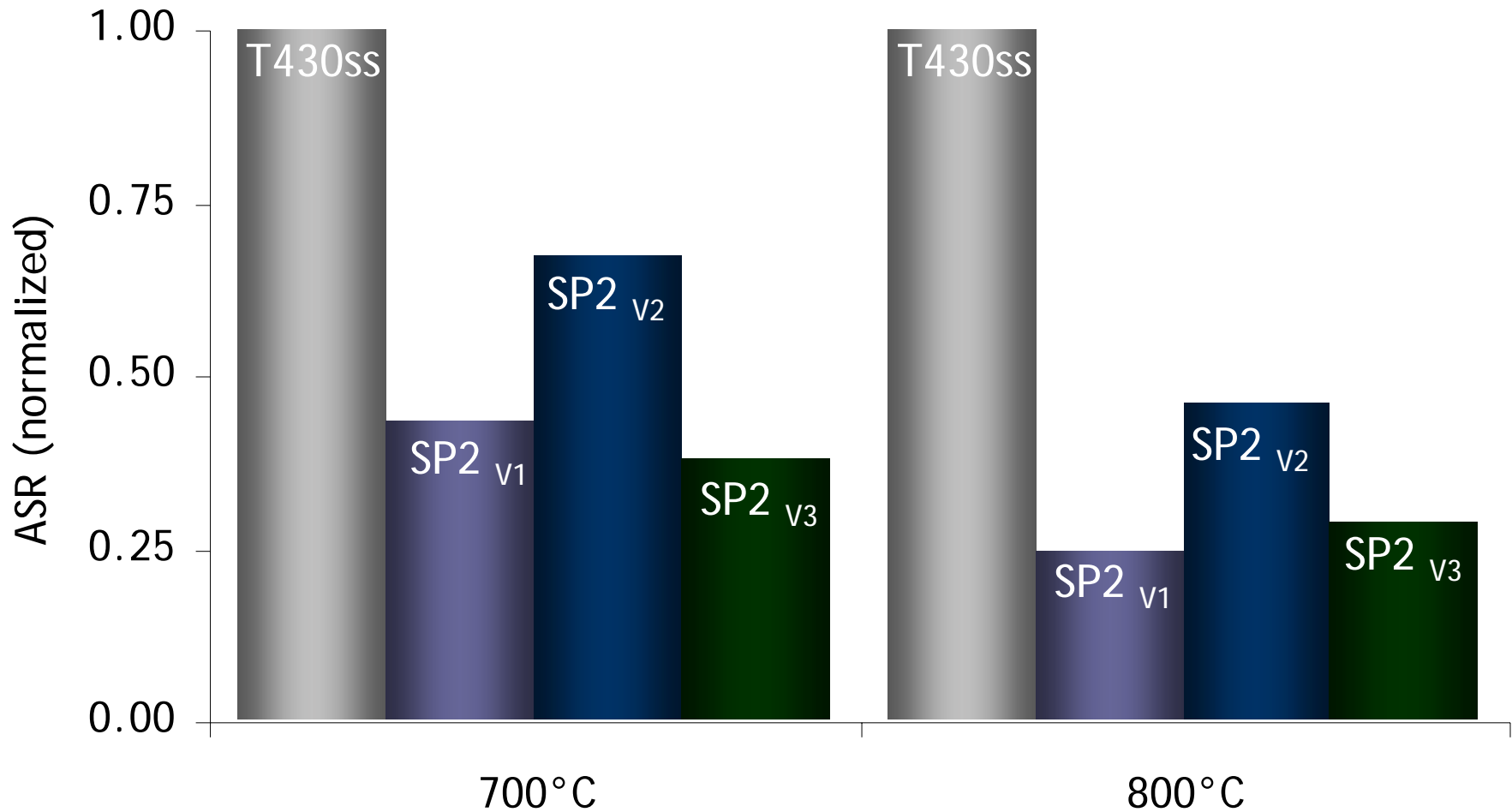
Effect of Aluminum Sequestration



Effect of Silicon Removal

- Silicon forms a very thin layer of electrically resistive silica at the scale/alloy interface
- Special processing removes silicon
 - No effect on oxidation resistance
 - Lower ASR
 - Effect magnified at higher temperatures

Effect of Silicon Removal



ASR measurement temperature (°C)

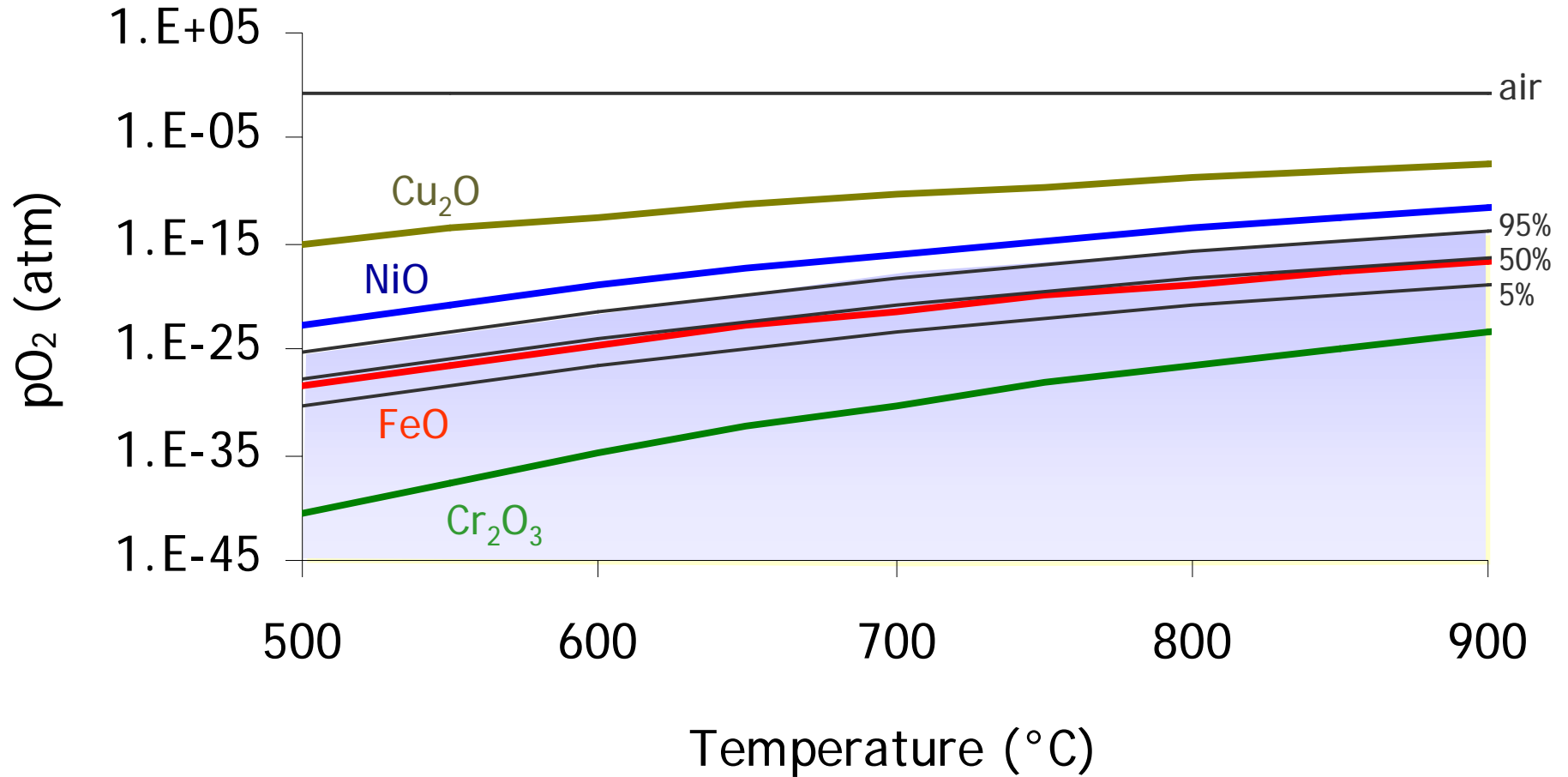
samples pre-oxidized in air for 500 hours at 800°C

Anode-Side Surface Modification Multi-Layered Metal Interconnects

Multi-Layered Metal Interconnects

- SOFC anode gas is a low-oxygen environment
 - Reducing to Cu, Ni
 - Partially reducing to Fe
 - Oxidizing to Cr, Al, Si

Materials Selection



Multi-Layered Metal Interconnects

- SOFC anode gas is a low-oxygen environment
- Most metals/alloys are not generally suitable for monolithic interconnects
 - Excessive oxidation on the cathode side
 - Incompatible physical properties
 - Cost
- Can be used as thin layers on ferritic stainless steel substrates

Multi-Layered Metal Interconnects

anode-side

Ni (UNS N02201), Cu (UNS C10100), Ni-32Cu (UNS N04400)

T430 stainless steel substrate (~80% of total thickness)

alloy 600 (UNS N06600)

cathode-side

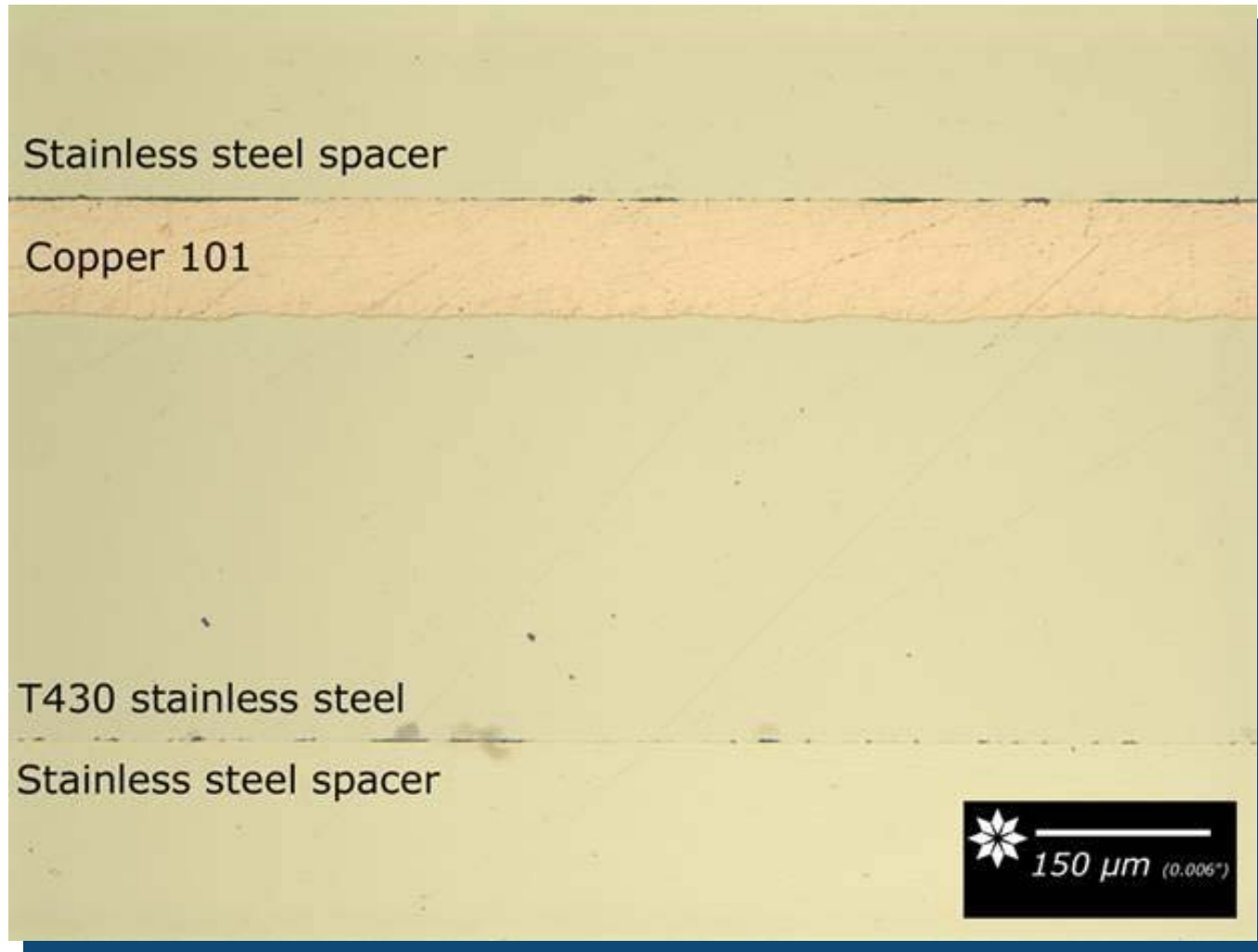
Bi-Layer Interconnect

substrate/cathode side - T430 stainless steel

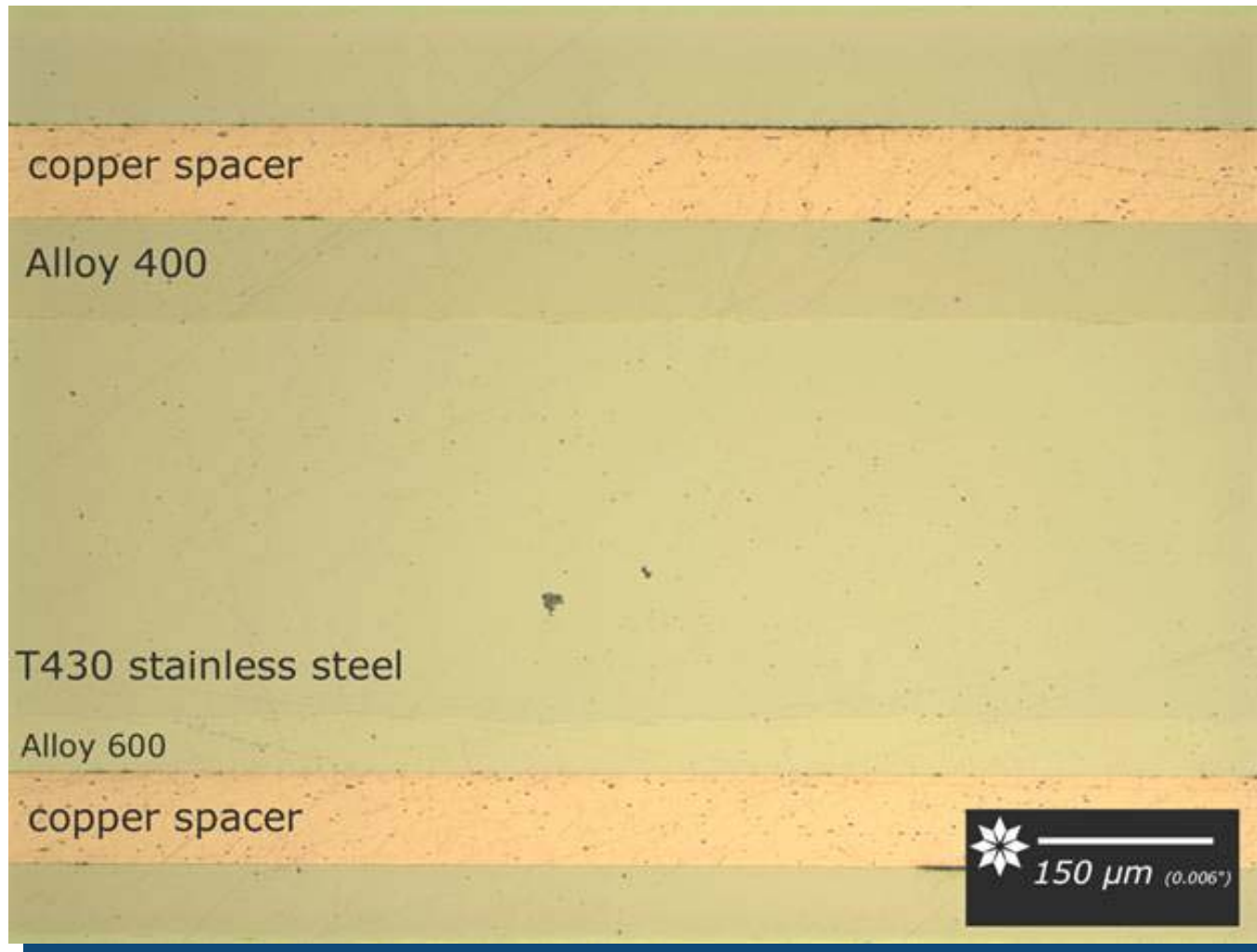


anode side - copper (Cu 101 alloy)

Bi-Layer Interconnect



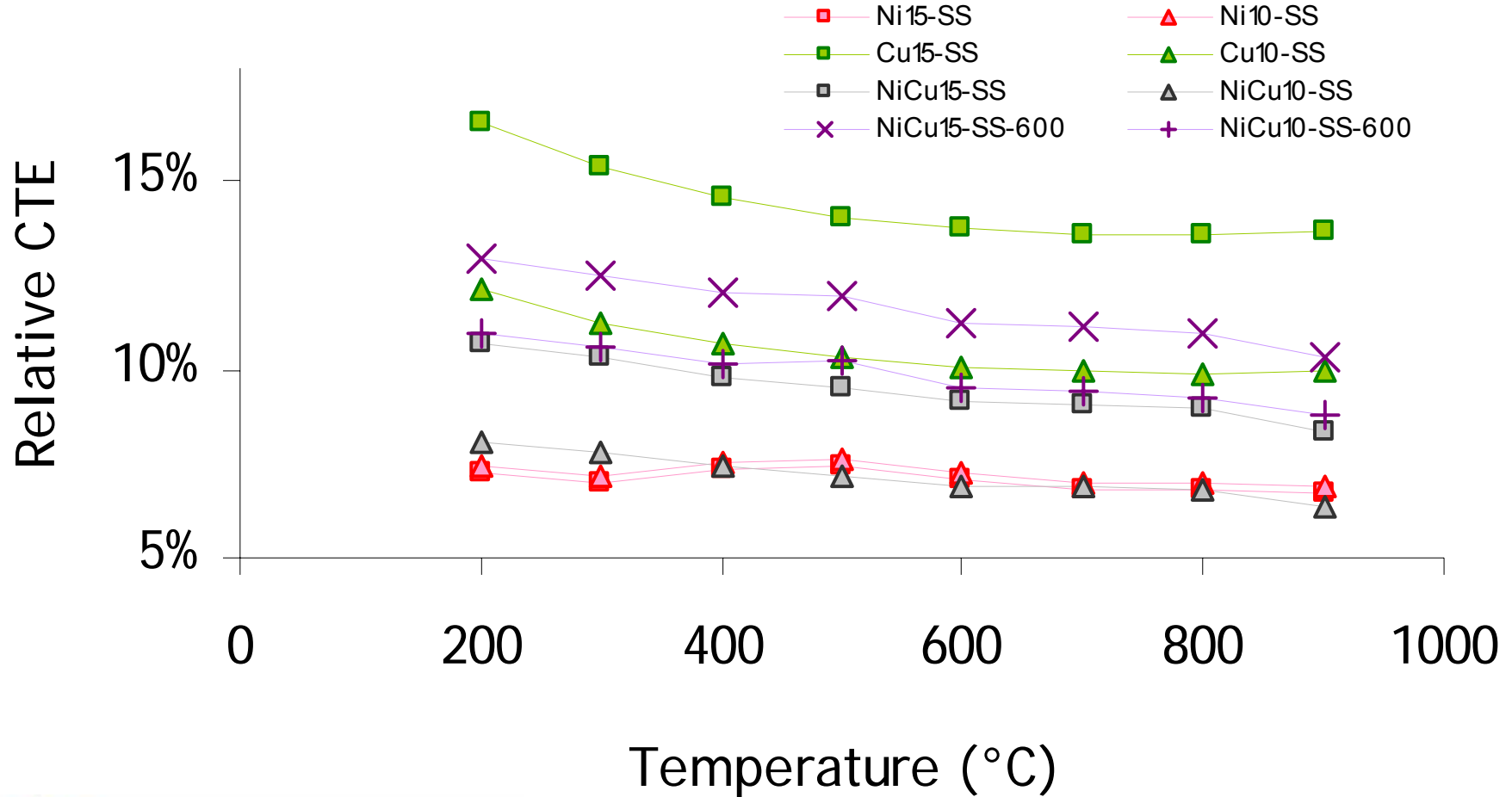
Tri-Layer Interconnect



Evaluation of Multi-Layered Interconnect Structures

- Physical properties
- Environmental exposures
 - Simulated anode gas (SAG)
 - Ar-4H₂-3%H₂O
 - Ar-4%CH₄-3%H₂O
 - Ar-4H₂-10%H₂O
 - Dual atmosphere
 - Air (cathode side)
 - Ar-4H₂-10%H₂O (anode side)
 - Durability (ΔT)

Estimated Linear CTE



Simulated Anode Gas Exposures

- Nickel surface remains bright and free of oxide scale
- Copper surface is mottled dark and metallic, particularly at higher p_{H_2O}
- Manganese oxide film observed to form on the Ni-32Cu alloy
 - MnO is relatively stable
 - Used a commercial alloy with a residual Mn level of approximately 0.4 wt. %

Simulated Anode Gas Exposures

Ni



1,372 hours at 800°C

Ar-4% H_2 -3% H_2O

Cu



Ni-32Cu



Simulated Anode Gas Exposures

Ni



1,221 hours at 800°C

Ar-4% H_2 -10% H_2O

Cu



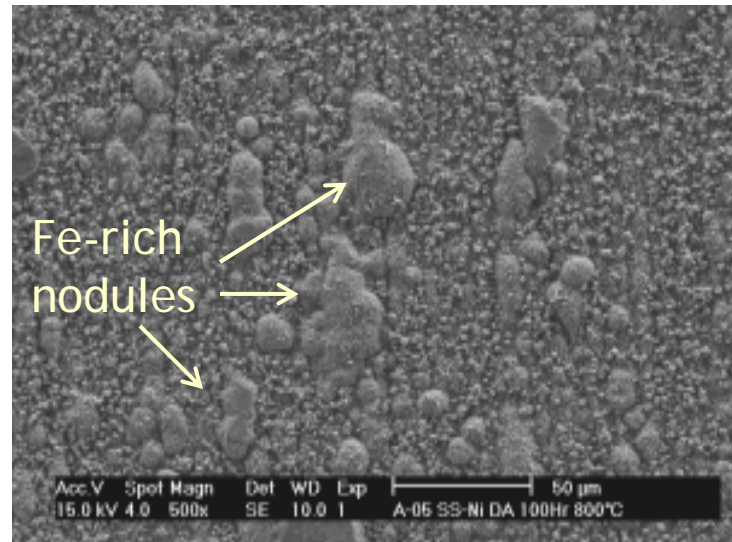
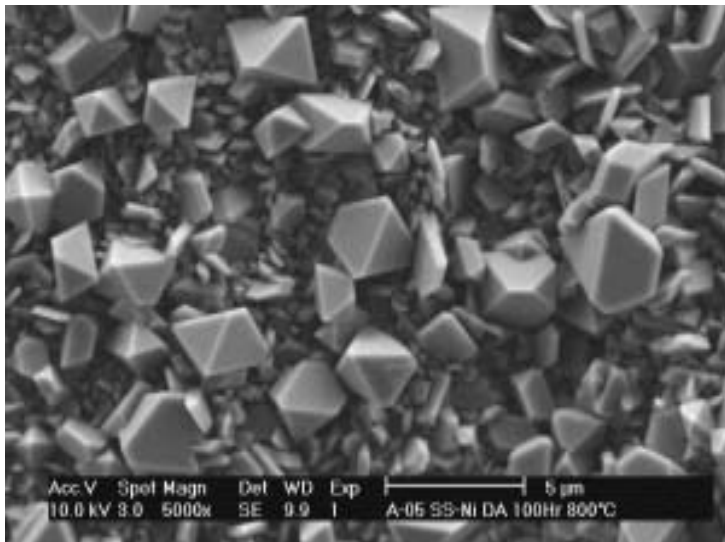
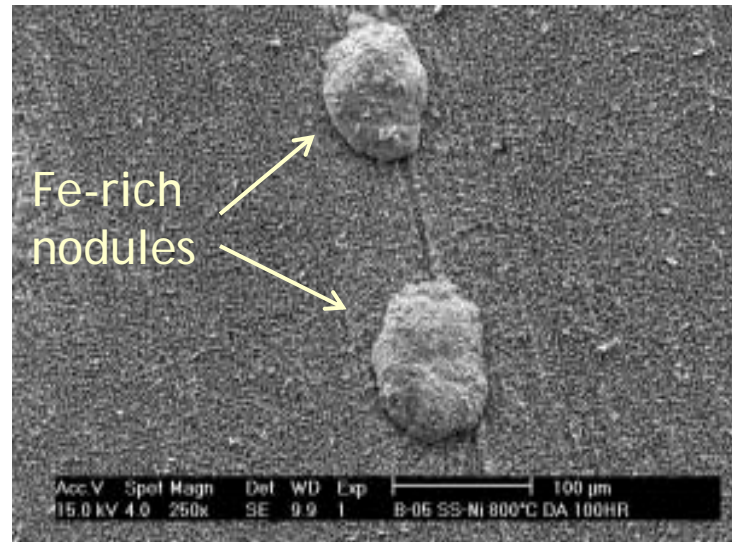
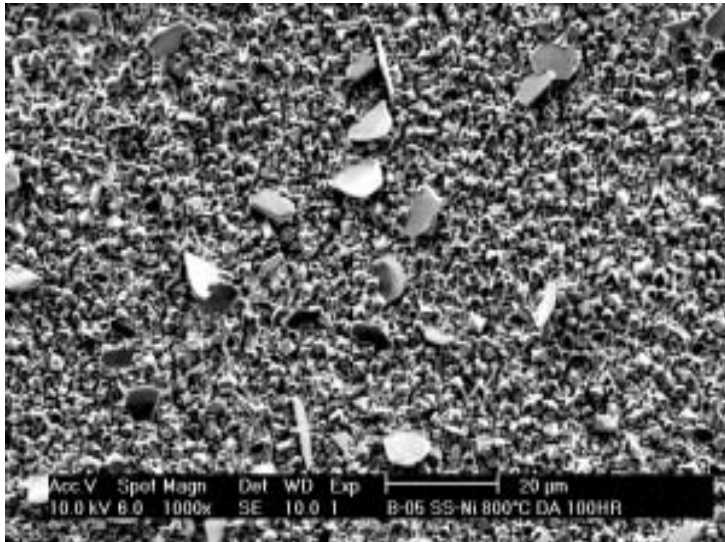
Ni-32Cu



Dual Atmosphere Exposures

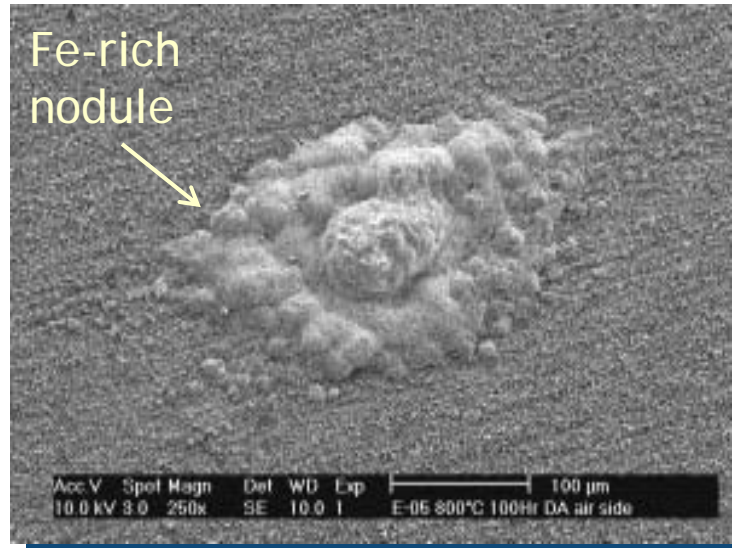
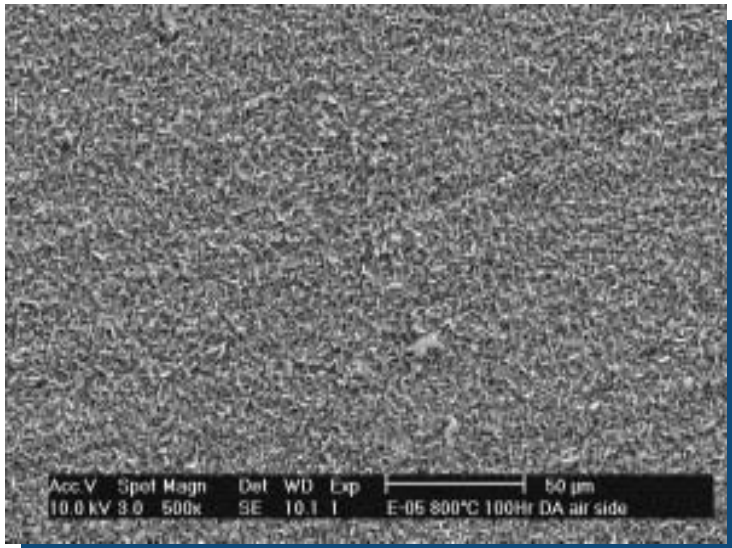
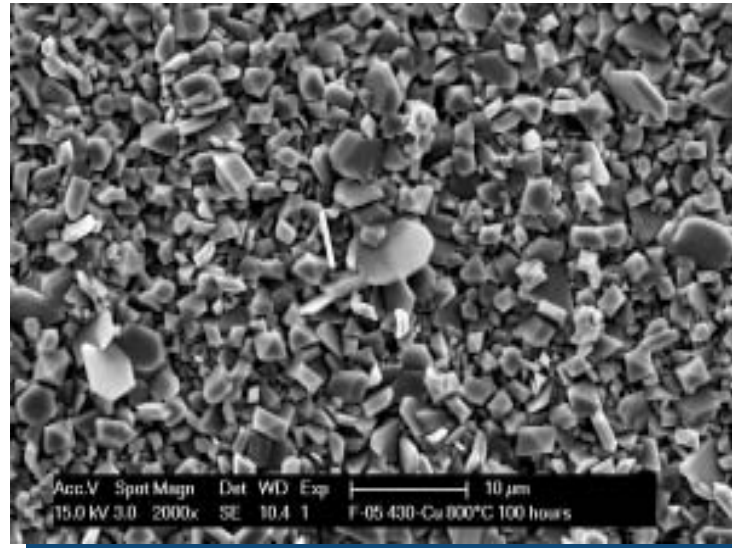
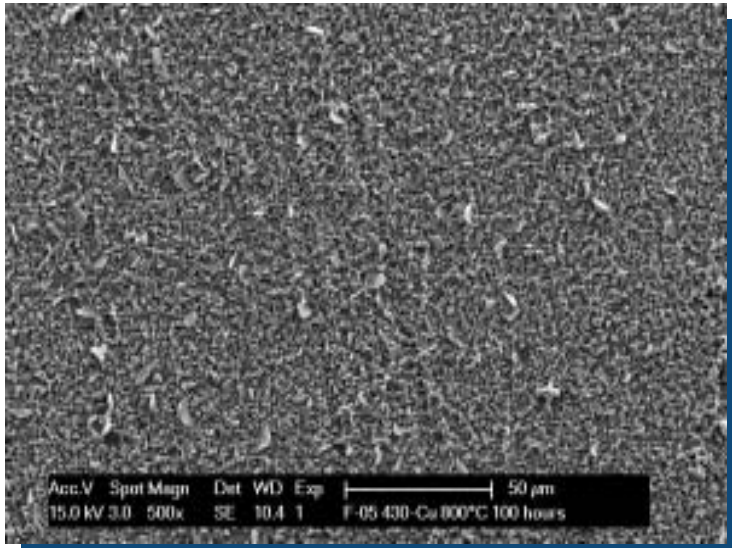
- Surface phases on the SAG side consistent with previous exposures
- Anode-side layers appear to provide some resistance to hydrogen migration
 - Fe-rich nodules form on Ni-SS specimens
 - One isolated nodule was found Cu-SS specimens
 - No nodules observed on NiCu-SS specimens

Nickel-Stainless Steel Composite



air side

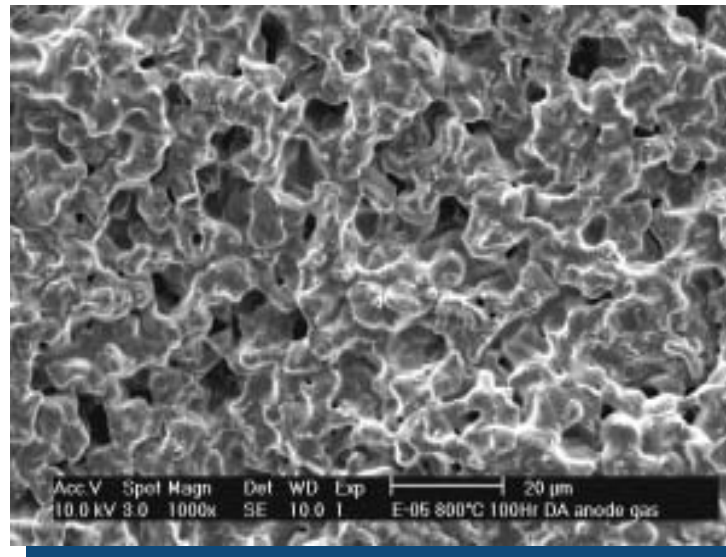
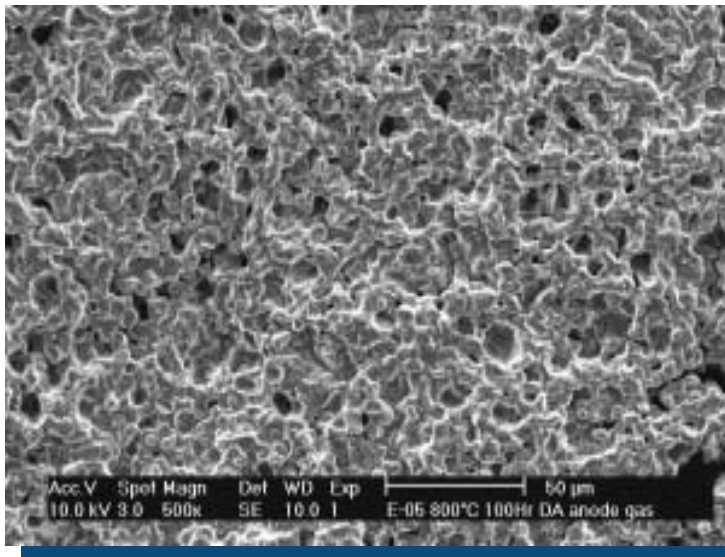
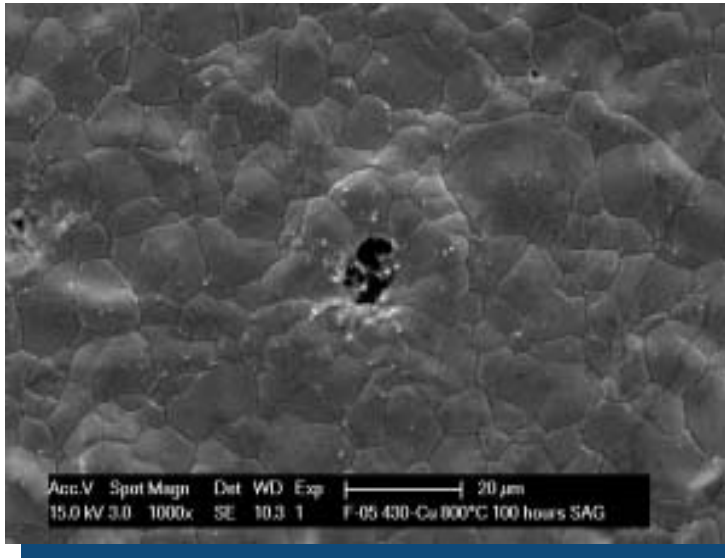
Copper-Stainless Steel Composite



air side

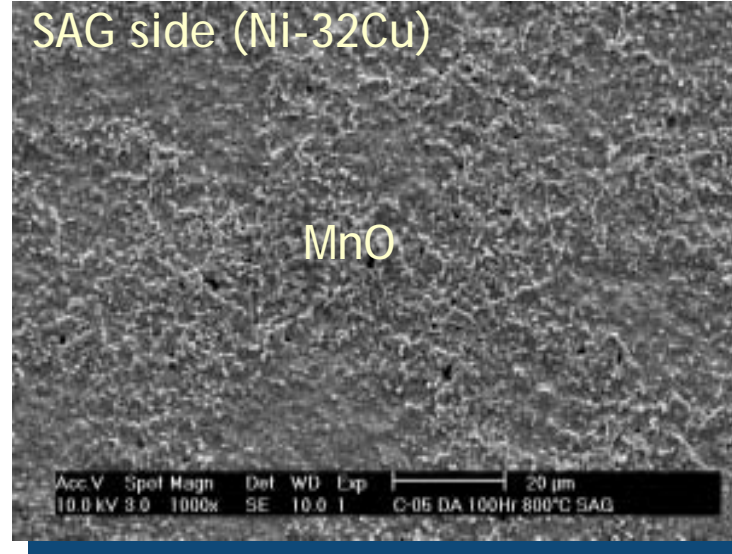
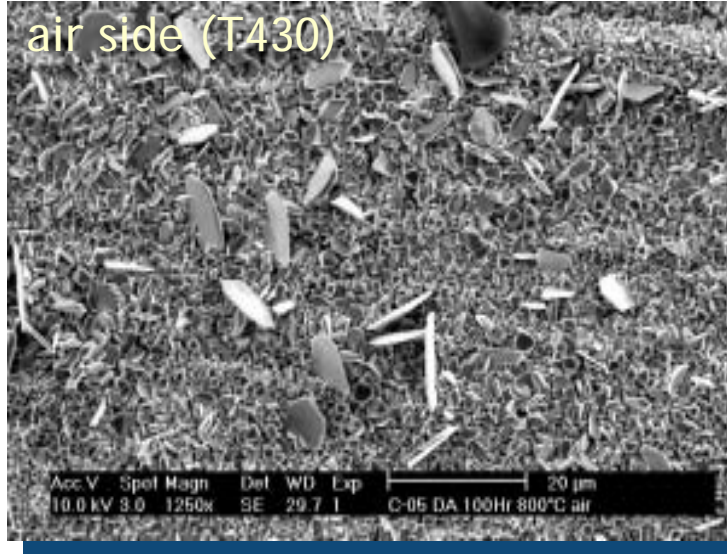
Copper-Stainless Steel Composite

copper layers appear
porous after exposure
to SAG

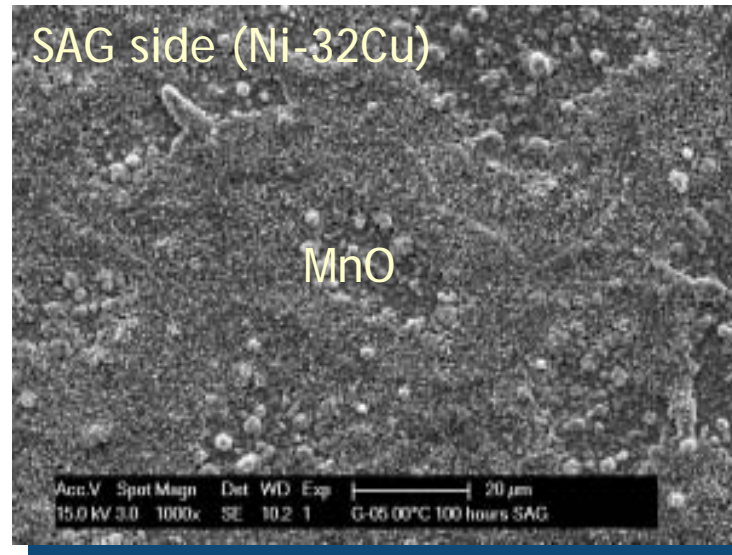
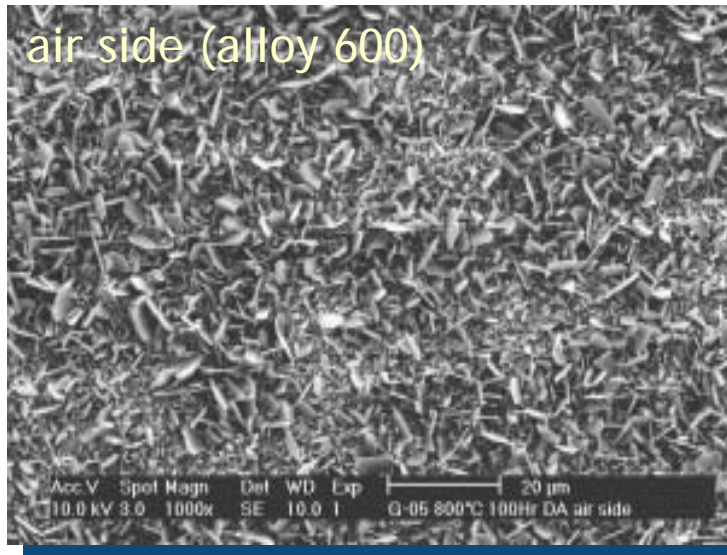


SAG side

NiCu-Stainless Steel Composite



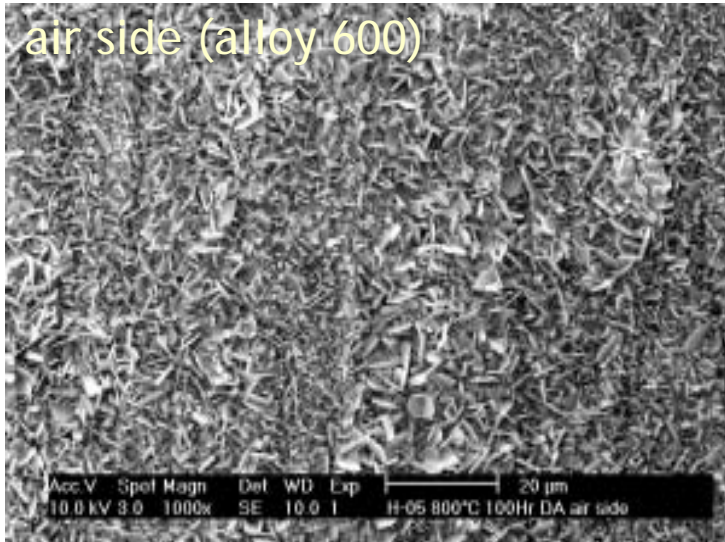
bi-layer



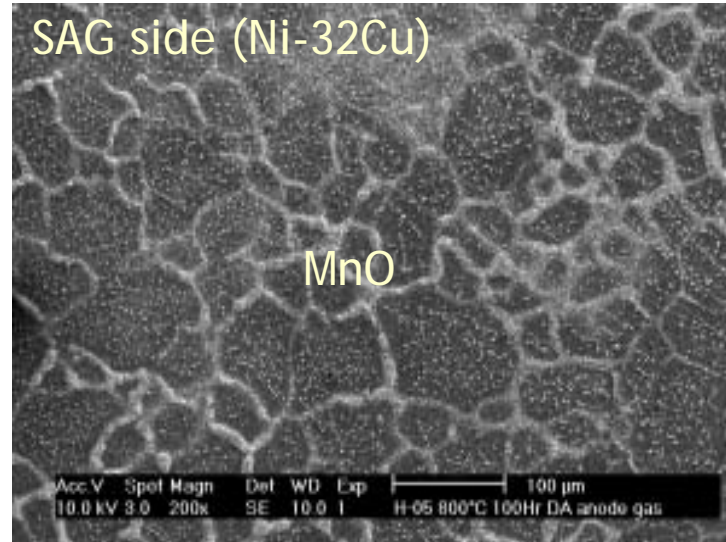
tri-layer

Tri-Layer Composite

air side (alloy 600)

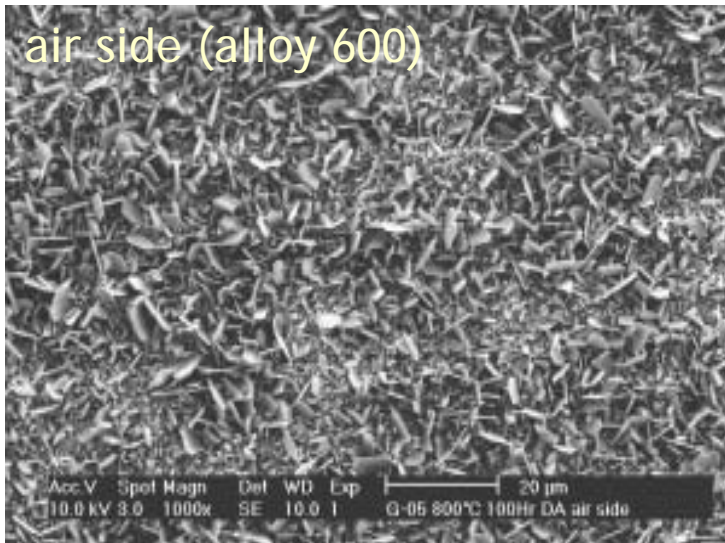


SAG side (Ni-32Cu)

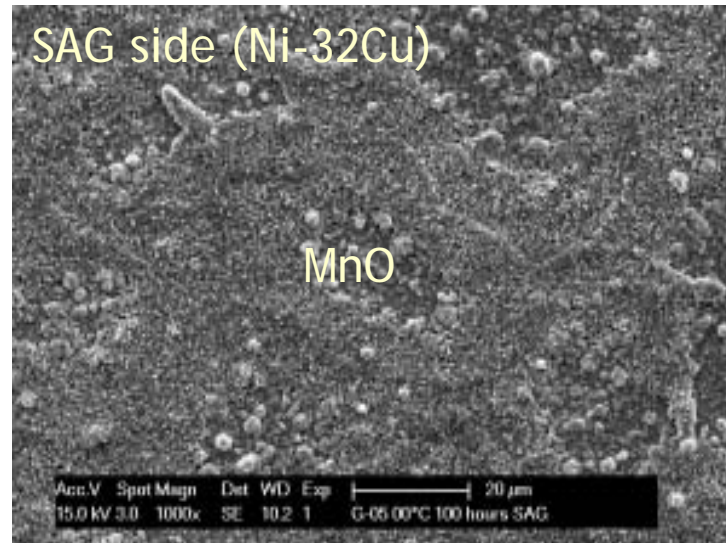


NiCu10-SS-600

air side (alloy 600)



SAG side (Ni-32Cu)



Summary

- Detrimental effects of aluminum and silicon can be reduced via process modifications
- Multi-layered interconnect structures have been tested and shown to be feasible
 - May reduce or eliminate oxidation on the anode side of the SOFC interconnect
 - Some of the alloys tested for anode-side layers may possibly reduce hydrogen transport (“dual atmosphere”) effects

Work in Progress

- Optimization and long-term durability testing of post-process treatments for ferritic stainless steel interconnects
- Refinement of alloying concepts for monolithic interconnects
- Further evaluation of oxidation-resistant, electrically conductive coatings for ferritic stainless steel interconnects

Work in Progress

- Further evaluation of interactions between the SOFC system and interconnect oxidation
- Refinement of techniques for evaluating the adhesion of oxides and coatings on SOFC interconnects (CMU)
- Further evaluation of silver-based cathode contact layers (WVU)

Acknowledgements

- NETL
 - Funding under projects DE-FC26-05NT42513 and DE-FC26-02NT41578
 - Ayyakkannu Manivannan - Program Manager
 - Lane Wilson
 - Wayne Surdoval
 - David Alman (Ce-coated samples)
- PNNL
 - Jeffry Stevenson (MnCo spinel-coated samples)
 - Prabhakar Singh
- Program Subcontractors/Contractors
 - Carnegie Mellon University - Professor Jack Beuth; A. Sawant
 - University of Pittsburgh - Professor Jerry Meier; W. Jackson, S. Laney
 - West Virginia University - Professor Bruce Kang; J. Sakacs

for additional information...

www.alleghenYTEchnologies.com

www.alleghenyludlum.com

James M. Rakowski

Senior Associate, M&PD

1.724.226.6483

jrakowski@alleghenyludlum.com



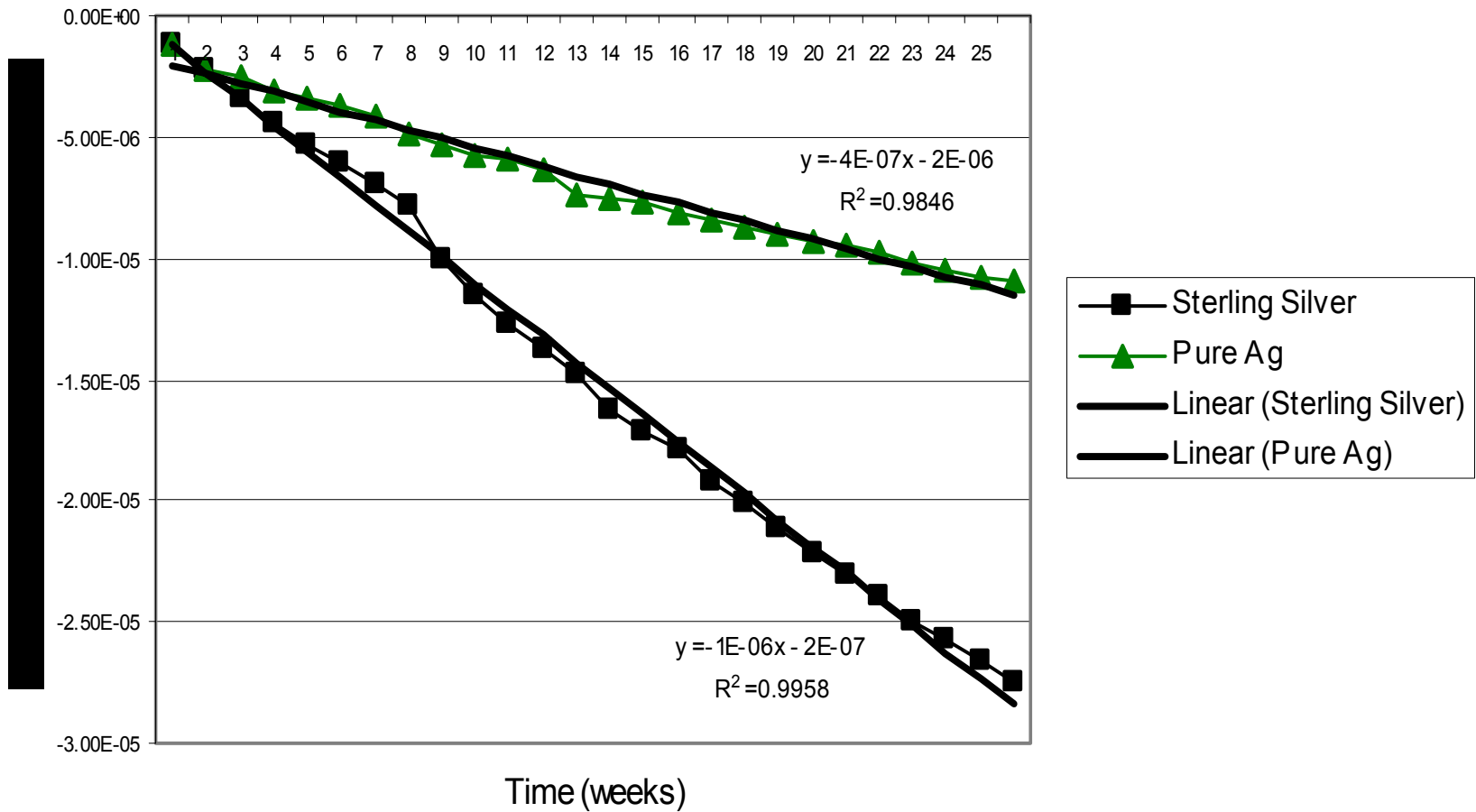


Overview

- Examination of candidate silver cermets for use as contacting material in the cathode chamber of the solid-oxide fuel cell.
- First-year research effort was on sterling silver
 - Thickness reduction data
 - Sterling silver samples vs. Pure silver samples
 - SEM analysis
 - Time series examination of changing sterling silver, pressed Ag/CuO, and pressed Ag/LSM surfaces

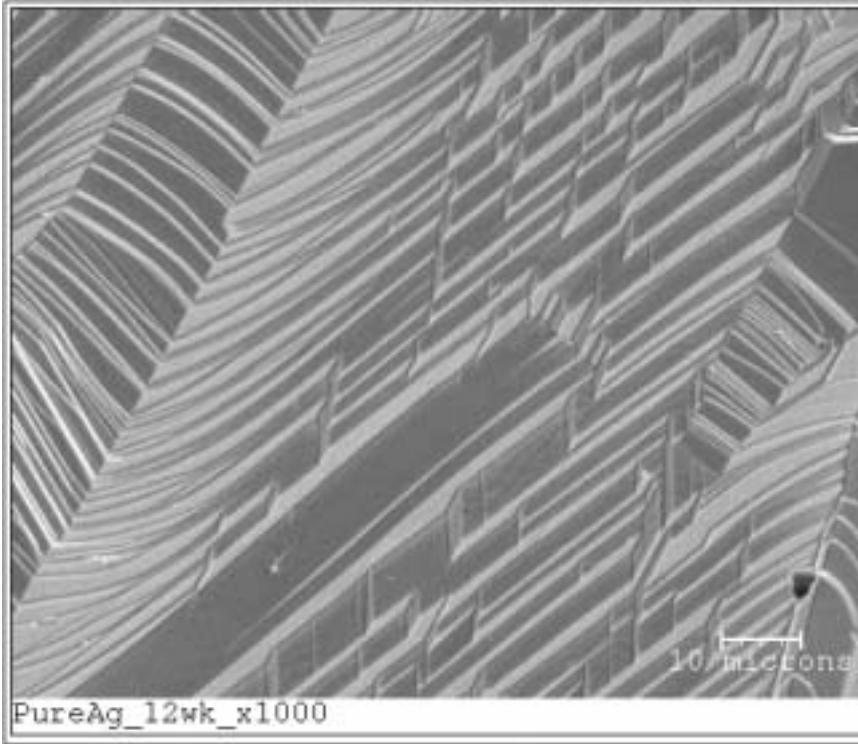


Cumulative Thickness Reduction; Silver, Sterling Silver





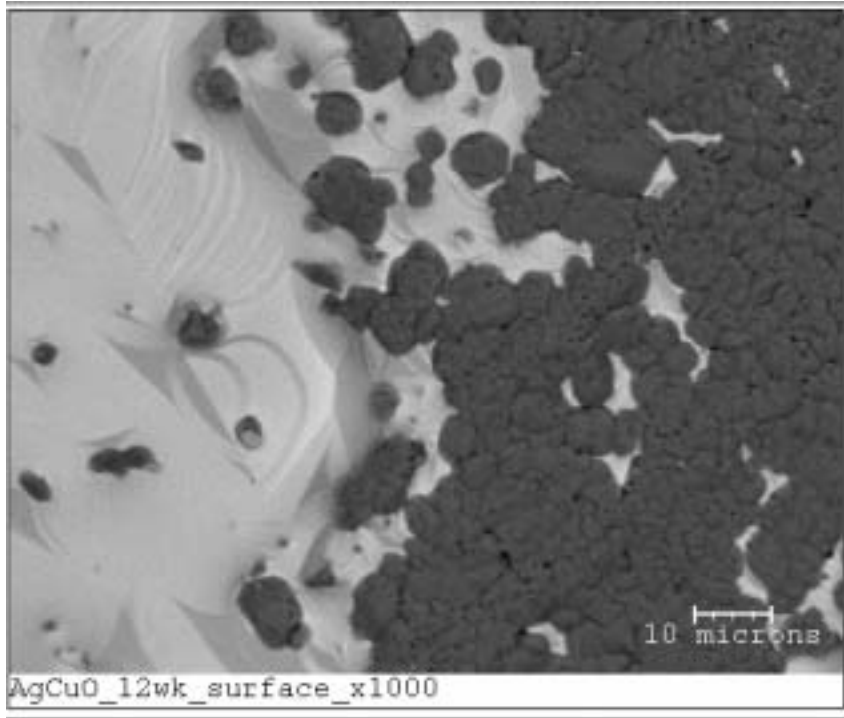
Pure silver exposed surface



- Sample exposed at 800C, 3 l/min air flow for 12-weeks
- Note surface step orientation
- Surface re-orientation to least favorable evaporation state
- SEM micrograph x1000



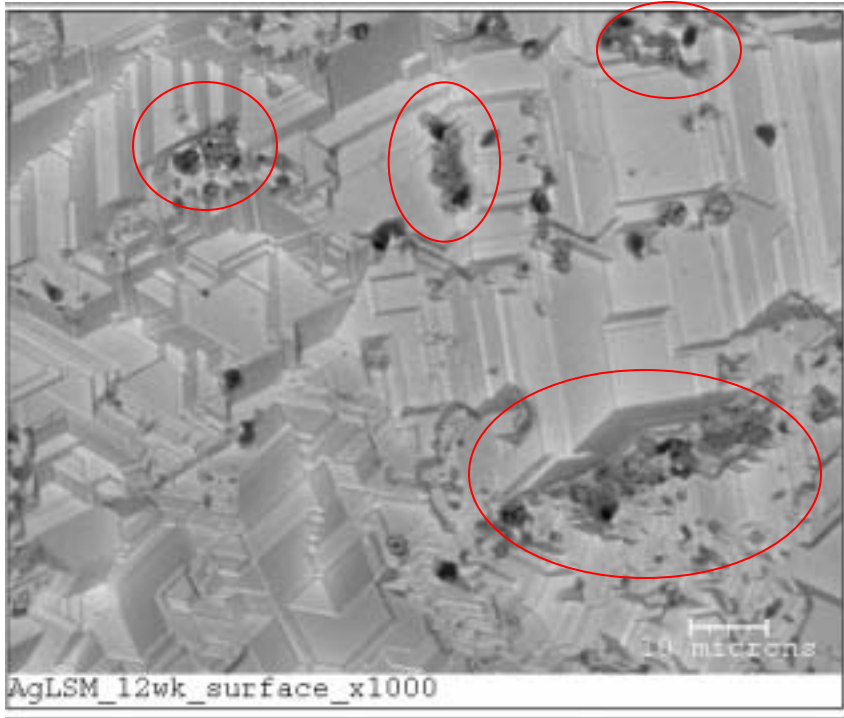
Silver/Copper-oxide exposed surface



- Sample fabricated by cold-pressing CuO powder (dark areas) into pure silver
- Exposed at 800C, 3 l/min air flow, for 12-weeks
- Silver surface orientation much less pronounced than with pure silver likely not resulting in least favorable evaporation state
- Appears evaporation more pronounced near CuO particles
- Backscatter image x1000



Silver/LSM exposed surface

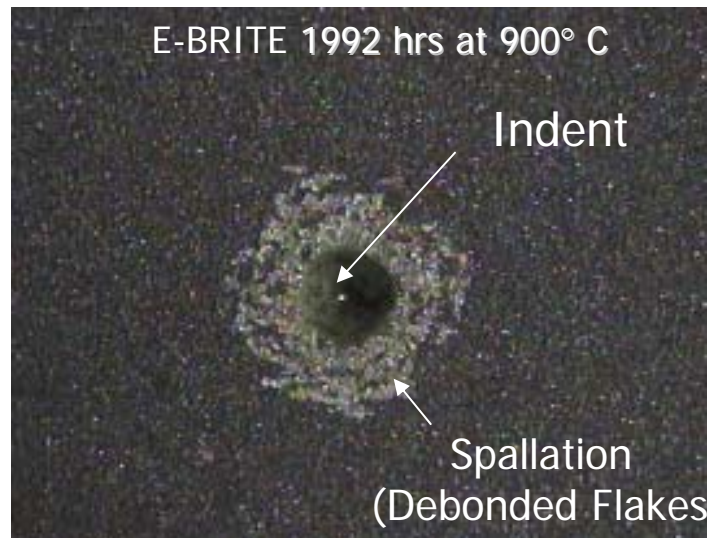


- Sample fabricated by cold-pressing LSM powder (circled in red) into pure silver
- Exposed at 800C, 3 l/min air flow, for 12-weeks
- Surface orientation similar to that of pure silver

Macro-Scale Indent Tests for Spallation Resistance

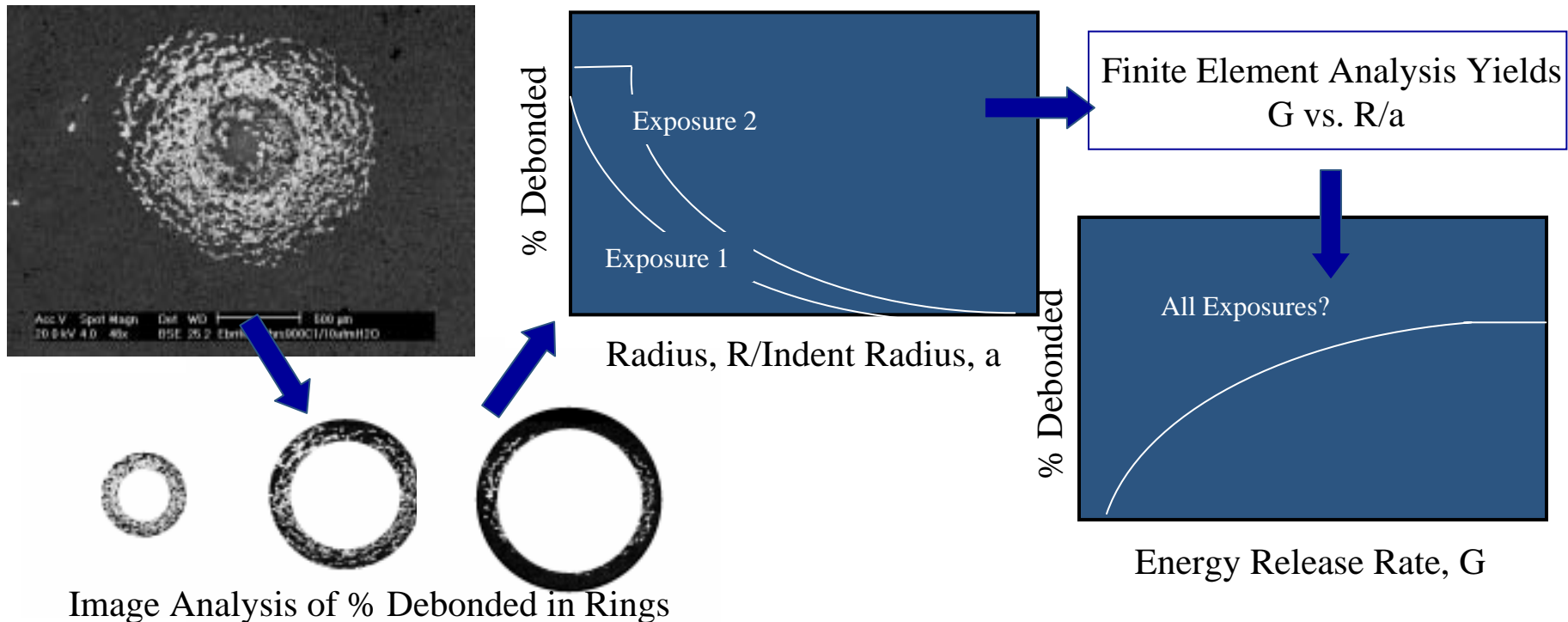
J. Beuth, Carnegie Mellon

- *Idea:* Use Indentation to Induce Spalls after Short Exposure Times.
- Use to Rapidly Evaluate Alloy Systems (From ATI) and Coated Alloy Systems (from Arcomac and PNNL)
- Rockwell Hardness Test Performed on Exposed Alloy/Scale Systems or Coated Alloy Systems. *Indent Diameter is just less than 1mm*
- Indented Specimens Show Small Spalls; Density of Spalls Decreases with Radius
- Easy Test to Perform/Easy for SECA Partners to Work into Their Test Programs
- For Alloy Systems: Spallation Changes with Exposure Related to *Scale Thickness*, *Scale Stress* and *Interface Toughness* Changes

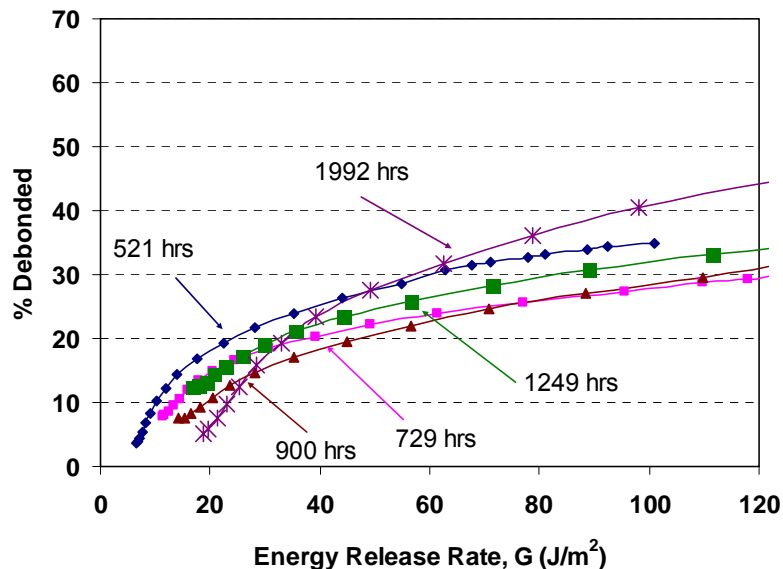
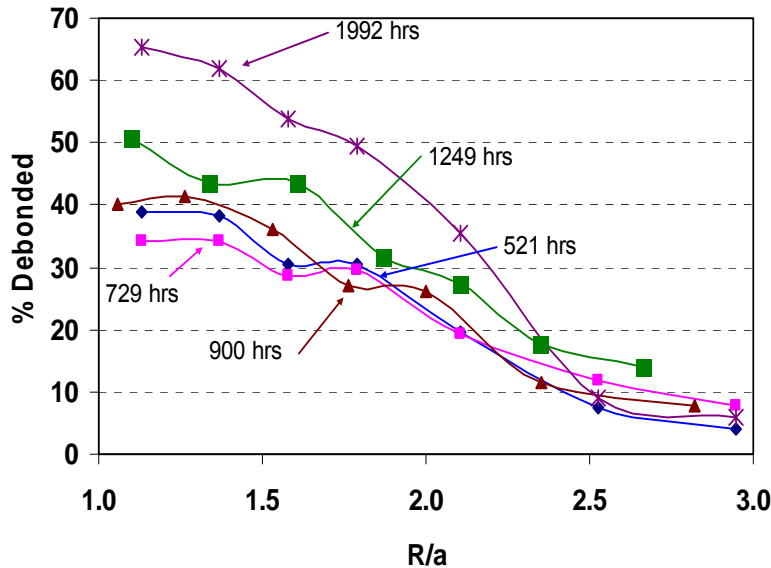


Macro Indent Test Procedures

- *First Plot:* Use Image Analysis to Quantify % of Debonded Scale vs. Radius
- *Second Plot:* Use Energy Release Rate (G) vs. Radius from Fracture Models to Plot % of Debonded Scale vs. G: *G Calculation Includes Measured Oxide Thickness Changes*
- *If a Single Curve Results for all Exposures, then Scale Stress and Interfacial Toughness are not Changing and Scale Thickness Controls Spallation*
- Use this Plot to Predict the % Debonding with Exposure



Macro-Scale Indent Results

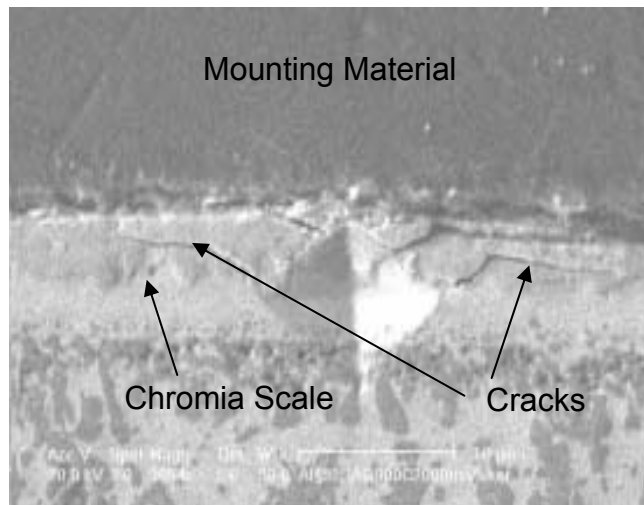


- E-BRITE Exposed at 900° C for up to 1992 hours
- Simulates 800° C Exposures to 25,000 hrs
- *First Plot:* A Fairly Steady Increase in Debonding is seen with Exposure
- *Second Plot:* Fracture Mechanics Analysis of Data Yields a Plot of % Debonding vs. Energy Release Rate
- Second Plot Indicates Stress and Toughness are Not Changing and Scale Thickness is Critical
- Can Relate a % Debonding Limit (an Interconnect Design Criterion on the Y Axis) to a Critical G (on the X Axis)
- Critical G can be Tied to a Critical Scale Thickness and Critical Exposure Time

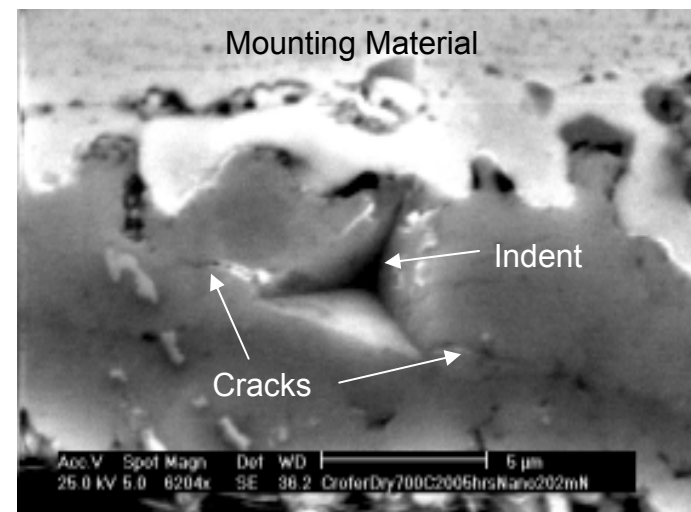
Micro/Nano-Scale Indent Tests

(Being Developed at Carnegie Mellon)

- An Independent, Direct Means of Determining Whether Scale or Interface Toughness are Changing with Exposure
- Procedure: Micro- or Nano-Indent Mounted Specimens from the Side, Induce Cracking in the Chromia Scale or at the Interface
- Extent of Cracking Tied to Toughness of the Chromia or Interface
- Micro Hardness Test Methods are More Easily Transferred to SECA Partners
- Also a Good Test for Probing Toughnesses of Brittle Layers and Interfaces in Complicated Subcell Structures



Micro (Vickers) Indent



Nano (Berkovich) Indent